FOR LOW FREQUENCY POWER AMPLIFY APPLICATION SILICON PNP EPITAXIAL PLANAR TYPE

DESCRIPTION

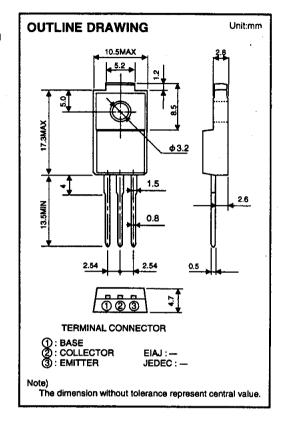
Mitsubishi 2SB1314 is a silicon PNP epitaxial planar type power transistor using insulated full mold package.

FEATURE

- ●High collector current lc=-3A,lcм=-5A
- ●High hFE hFE=150 to 500
- ●Full moid package with heat sink
- ●High voltage VcEo=-60V
- ●Low collector to emitter saturation voltage VCE(sat)=-0.5V max(@Ic=-2A,IB=-0.2A)

APPLICATION

Power supply circuit, solenoid drive.



MAXIMUM RATINGS (Ta=25°C)

Symbol	Parameter		Ratings	Unit
Vсво	Collector to Base voltage		-60	V
VEBO	Emitter to Base voltage		-7	V
VCEO	Collector to Emitter voltage		-60	V
Ісм	Peak collector current		-5	Α
lc	Collector current		-3	Α
Pc	Collector dissipation	(Ta=25℃)	2	W
		(Tc=25°C)	15	W
T _j	Junction temperature		+150	ా
Tstg	Storage temperature		-55 to +150	ೡ

ELECTRICAL CHARACTERISTICS (Ta=25℃)

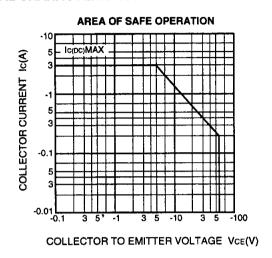
Symbol	Parameter	Test conditions	Limits			Unit
			Min	Тур	Max	1 0/111
V(BR)CBO	C to B break down voltage	Ic=-100 μ A	-60			V
V(BR)EBO	E to B break down voltage	IE=-100 μ A,IC=0	-7			V
V(BR)CEO	C to E break down voltage	Ic=-1mA,RBE=∞	-60			V
Ісво	Collector cut off current	Vcb=-50V,IE=0			-1	μΑ
IEBO	Emitter cut off current	VEB=-6V,IC=0			-1	μΑ
hfe *	DC forward current gain	VcE=-5V,lc=-500mA	150		500	-
VCE(sat)	C to E saturation voltage	Ic=-2A,IB=-0.2A			-0.5	V
fτ	Gain band width product	Vce=-6V,le=10mA		100		MHz

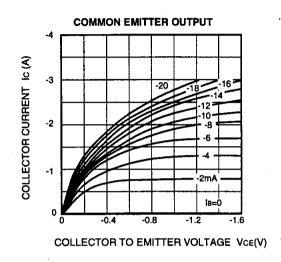
^{* :} It shows her classification in right table.

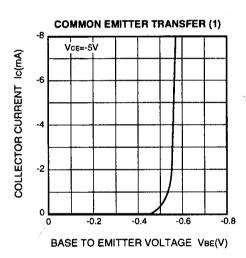
item	E	F
hFE	150 to 300	250 to 500

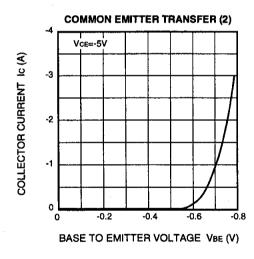
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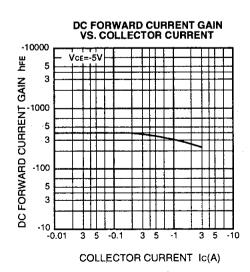
TYPICAL CHARACTERISTICS

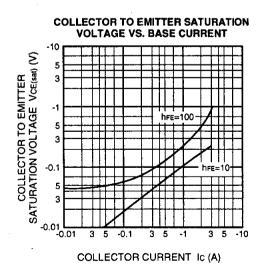












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http://www.idc-com.co.jp 6-41, TSUKUBA, ISAHAYA, NAGASAKI, 854-0065, JAPAN

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